

Basic information	
<b>2018/2947(DEA)</b> DEA - Delegated acts procedure	Procedure completed - delegated act enters into force
Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages  Supplementing <a href="#">2008/0240(COD)</a>  <b>Subject</b>  3.40.06 Electronics, electrotechnical industries, ICT, robotics 3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)	

Key players			
European Parliament	<b>Committee responsible</b>	<b>Rapporteur</b>	<b>Appointed</b>
	<div>ENVI</div> Environment, Public Health and Food Safety		

Key events			
Date	Event	Reference	Summary
16/11/2018	Non-legislative basic document published	<a href="#">C(2018)07499</a>	
16/11/2018	Initial period for examining delegated act 2 month(s)		
28/11/2018	Committee referral announced in Parliament		
24/01/2019	Delegated act not objected by Parliament		

Technical information	
<b>Procedure reference</b>	2018/2947(DEA)
<b>Procedure type</b>	DEA - Delegated acts procedure
<b>Procedure subtype</b>	Examination of delegated act
<b>Amendments and repeals</b>	Supplementing <a href="#">2008/0240(COD)</a>
<b>Stage reached in procedure</b>	Procedure completed - delegated act enters into force
<b>Committee dossier</b>	ENVI/8/15029

Documentation gateway			
European Commission			
Document type	Reference	Date	Summary

Non-legislative basic document	<a href="#">C(2018)07499</a>	16/11/2018	
Document attached to the procedure	C(2025)5889	25/08/2025	